DS10BR254 1.5 Gbps 1:4 LVDS Repeater



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General Description

The DS10BR254 is a 1.5 Gbps 1:4 LVDS repeater optimized for high-speed signal routing and distribution over FR-4 printed circuit board backplanes and balanced cables. Fully differential signal paths ensure exceptional signal integrity and noise immunity.

The device has two different LVDS input channels and a select pin determines which input is active. A loss-of-signal ($\overline{\text{LOS}}$) circuit monitors both input channels and a unique $\overline{\text{LOS}}$ pin is asserted when no signal is detected at that input.

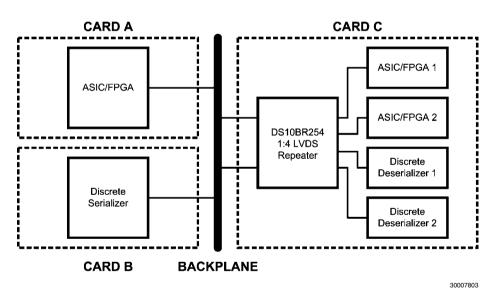
Wide input common mode range allows the switch to accept signals with LVDS, CML and LVPECL levels; the output levels are LVDS. A very small package footprint requires a minimal space on the board while the flow-through pinout allows easy board layout. Each differential input and output is internally terminated with a 100Ω resistor to lower device return losses, reduce component count and further minimize board space.

Features

- DC 1.5 Gbps low jitter, low skew, low power operation
- Wide Input Common Mode Voltage Range allows for DCcoupled interface to LVDS, CML and LVPECL drivers
- Redundant inputs
- LOS circuitry detects open inputs fault condition
- Integrated 100Ω input and output terminations
 8 kV ESD on LVDS I/O pins protects adjoining components
- Small 6 mm x 6 mm LLP-40 space saving package

Applications

- Clock distribution
- Clock and data buffering and muxing
- OC-12 / STM-4
- SD/HD SDI Routers

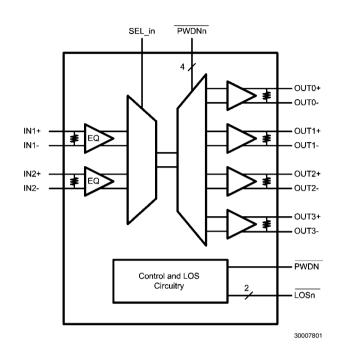


Typical Application

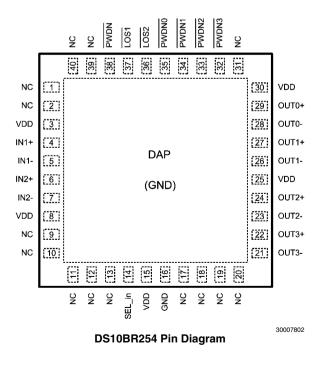
Ordering Code

	NSID	Function
ww	DS10BR254TSQ	1:4 Repeater

Block Diagram



Connection Diagram



DS10BR254

Pin Descriptions

Pin Name www.DataSheet4U.cor	Pin Number	I/O, Туре	Pin Description
IN1+, IN1-, IN2+, IN2-,	4, 5, 6, 7,	I, LVDS	Inverting and non-inverting high speed LVDS input pins.
OUT0+, OUT0-, OUT1+, OUT1-, OUT2+, OUT2-, OUT3+, OUT3-	29, 28, 27, 26, 24, 23, 22, 21	O, LVDS	Inverting and non-inverting high speed LVDS output pins.
SEL_in	14	I, LVCMOS	This pin selects which LVDS input is active.
LOS1, LOS2	37, 36	O, LVCMOS	Loss Of Signal output pins, <u>LOSn</u> report when an open input fault condition is detected at the input, INn. These are open drain outputs. External pull up resistors are required.
PWDN0, PWDN1, PWDN2, PWDN3	35, 34 33, 32	I, LVCMOS	Channel output power down pin. When the PWDNn is set to L, the channel output OUTn is in the power down mode.
PWDN	38	I, LVCMOS	Device power down pin. When the $\overline{\text{PWDN}}$ is set to L, the device is in the power down mode.
VDD	3, 8, 15,25, 30	Power	Power supply pins.
GND	16, DAP	Power	Ground pin and a pad (DAP - die attach pad).
NC	1, 2 9, 10, 11, 12, 13, 17, 18, 19, 20, 31, 39, 40	NC	NO CONNECT pins. May be left floating.

Absolute Maximum Ratings (Note 4)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage	-0.3V to +4V
LVCMOS Input Voltage	–0.3V to (V _{CC} + 0.3V)
LVCMOS Output Voltage	–0.3V to (V _{CC} + 0.3V)
LVDS Input Voltage	-0.3V to +4V
LVDS Differential Input Voltage	0.0V to +1V
LVDS Output Voltage	–0.3V to (V _{CC} + 0.3V)
LVDS Differential Output Voltage	0.0V to +1V
LVDS Output Short Circuit Current Duration	5 ms
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature Range	
Soldering (4 sec.)	+260°C
Maximum Package Power Dissipati	on at 25°C
SQA Package	4.65W
Derate SQA Package	37.2 mW/°C above +25°C

Package Thermal Resistance

θ _{JA}	+26.9°C/W
θ _{JC}	+3.8°C/W
ESD Susceptibility	
HBM (Note 1)	≥8 kV
MM (Note 2)	≥250V
CDM (Note 3)	≥1250V

Note 1: Human Body Model, applicable std. JESD22-A114C Note 2: Machine Model, applicable std. JESD22-A115-A Note 3: Field Induced Charge Device Model, applicable std. JESD22-C101-C

Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage (V _{CC})	3.0	3.3	3.6	V
Receiver Differential Input Voltage (V _{ID})	0		1	V
Operating Free Air Temperature (T _A)	-40	+25	+85	°C

Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified. (Notes 5, 6, 7)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
LVCMOS	S DC SPECIFICATIONS					
V _{IH}	High Level Input Voltage		2.0		V_{DD}	V
V _{IL}	Low Level Input Voltage		GND		0.8	V
I _{IH}	High Level Input Current	$V_{\rm IN} = 3.6V$		0	±10	μA
I _{IL}	Low Level Input Current	$V_{CC} = 3.6V$ $V_{IN} = GND$ $V_{CC} = 3.6V$		0	±10	μA
V _{CL}	Input Clamp Voltage	$I_{CL} = -18 \text{ mA}, V_{CC} = 0 \text{V}$		-0.9	-1.5	V
V _{OL}	Low Level Output Voltage	I _{OL} = 4 mA		0.26	0.4	V
LVDS IN	PUT DC SPECIFICATIONS			•		
V _{ID}	Input Differential Voltage		0		1	V
V _{TH}	Differential Input High Threshold	$V_{CM} = +0.05V \text{ or } V_{CC} - 0.05V$		0	+100	mV
V _{TL}	Differential Input Low Threshold		-100	0		mV
V _{CMR}	Common Mode Voltage Range	V _{ID} = 100 mV	0.05		V _{CC} - 0.05	V
I _{IN}	Input Current	V _{IN} = +3.6V or 0V V _{CC} = 3.6V or 0V		±1	±10	μA
C _{IN}	Input Capacitance	Any LVDS Input Pin to GND		1.7		pF
R _{IN}	Input Termination Resistor	Between IN+ and IN-		100		Ω

Symbol	Parameter	Conditions	Min	Тур	Max	Units			
LVDS O	LVDS OUTPUT DC SPECIFICATIONS								
V _{OD}	Differential Output Voltage		250	350	450	mV			
ΔV _{OD}	Change in Magnitude of V _{OD} for Complimentary Output States	$R_L = 100\Omega$	-35		35	mV			
V _{OS}	Offset Voltage		1.05	1.2	1.375	V			
ΔV_{OS}	Change in Magnitude of V _{OS} for Complimentary Output States	$R_{L} = 100\Omega$	-35		35	mV			
I _{os}	Output Short Circuit Current (Note 8)	OUT to GND		-35	-55	mA			
		OUT to V _{CC}		7	55	mA			
C _{OUT}	Output Capacitance	Any LVDS Output Pin to GND		1.2		pF			
R _{OUT}	Output Termination Resistor	Between OUT+ and OUT-		100		Ω			
SUPPLY CURRENT									
I _{CC}	Supply Current	PWDN = H		113	135	mA			
I _{ccz}	Power Down Supply Current	PWDN = L		50	60	mA			

Note 4: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions.

Note 5: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 6: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except V_{OD} and ΔV_{OD} .

Note 7: Typical values represent most likely parametric norms for $V_{CC} = +3.3V$ and $T_A = +25^{\circ}C$, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 8: Output short circuit current (I_{OS}) is specified as magnitude only, minus sign indicates direction only.

AC Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

ww.DSymbolt4	J.com Parameter	Cond	litions	Min	Тур	Max	Units
LVDS OUTPUT	AC SPECIFICATIONS						
t _{PLHD}	Differential Propagation Delay Low to High (Note 11)				440	650	ps
t _{PHLD}	Differential Propagation Delay High to Low (Note 11)	- R _L = 100Ω			400	650	ps
t _{SKD1}	Pulse Skew It _{PLHD} – t _{PHLD} I (Notes 11, 12)				40	100	ps
t _{SKD2}	Channel to Channel Skew (Notes 11, 13)				40	125	ps
t _{SKD3}	Part to Part Skew (Notes 11, 14)				50	200	ps
t _{LHT}	Rise Time (Note 11)	D = 4000			150	300	ps
t _{HLT}	Fall Time (Note 11)	R _L = 100Ω			150	300	ps
t _{on}	Any PWDN to Output Active Time				8	20	μs
t _{OFF}	Any PWDN to Output Inactive Time				5	12	ns
t _{SEL}	Select Time				5	12	ns
JITTER PERFO	DRMANCE (Note 11)						
t _{RJ1}		V _{ID} = 350 mV	135 MHz		0.5	1	ps
t _{RJ2}	Random Jitter	V _{CM} = 1.2V	311 MHz		0.5	1	ps
t _{RJ3}	(RMS Value) (Note 15)	Clock (RZ)	503 MHz		0.5	1	ps
t _{RJ4}			750 MHz		0.5	1	ps
t _{DJ1}		V _{ID} = 350 mV	270 Mbps		6	22	ps
t _{DJ2}	Deterministic Jitter	$V_{CM} = 1.2V$	622 Mbps		6	21	ps
t _{DJ3}	── (Peak to Peak Value) ── (Note 16)	K28.5 (NRZ)	1.0625 Gbps		9	18	ps
t _{DJ4}			1.5 Gbps		9	17	ps
t _{TJ1}		V _{ID} = 350 mV	270 Mbps		0.01	0.03	UI _{P-P}
t _{TJ2}	Total Jitter	V _{CM} = 1.2V	622 Mbps		0.01	0.03	UI _{P-P}
t _{TJ3}	(Note 17)	PRBS-23 (NRZ)	1.0625 Gbps		0.01	0.04	UI _{P-P}
t _{TJ4}			1.5 Gbps		0.01	0.06	UI _{P-P}

Note 9: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 10: Typical values represent most likely parametric norms for V_{CC} = +3.3V and T_A = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 11: Specification is guaranteed by characterization and is not tested in production.

Note 12: t_{SKD1}, It_{PLHD} – t_{PHLD}, Pulse Skew, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

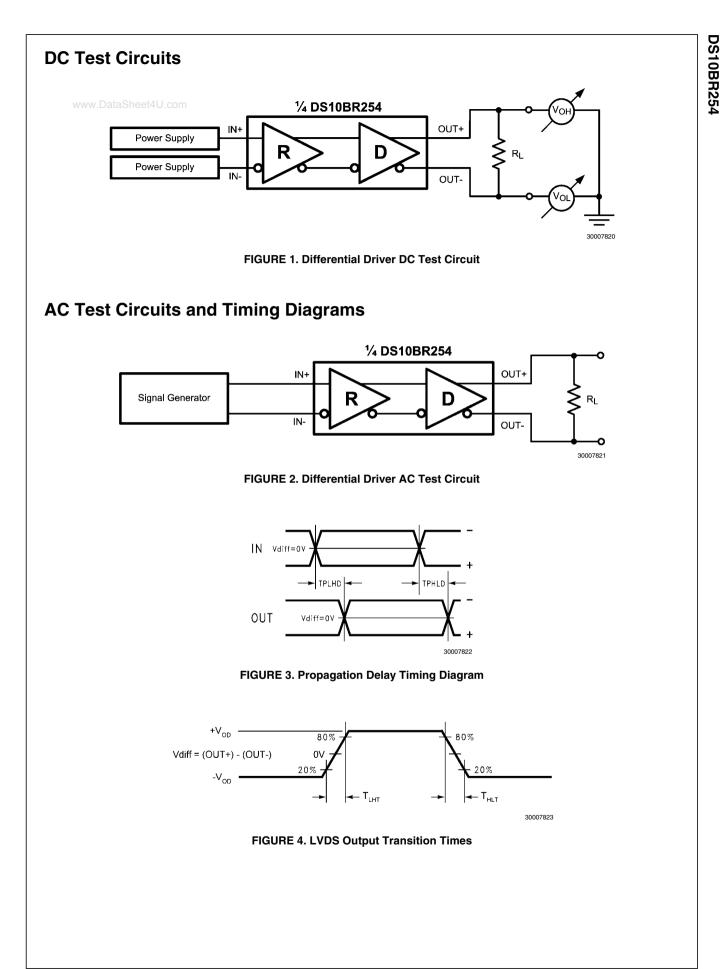
Note 13: t_{SKD2}, Channel to Channel Skew, is the difference in propagation delay (t_{PLHD} or t_{PHLD}) among all output channels in Broadcast mode (any one input to all outputs).

Note 14: t_{SKD3} , Part to Part Skew, is defined as the difference between the minimum and maximum differential propagation delays. This specification applies to devices at the same V_{CC} and within 5°C of each other within the operating temperature range.

Note 15: Measured on a clock edge with a histogram and an acummulation of 1500 histogram hits. Input stimulus jitter is subtracted geometrically.

Note 16: Tested with a combination of the 1100000101 (K28.5+ character) and 0011111010 (K28.5- character) patterns. Input stimulus jitter is subtracted algebraically.

Note 17: Measured on an eye diagram with a histogram and an acummulation of 3500 histogram hits. Input stimulus jitter is subtracted.



Functional Description The DS10BR254 is a 1.5 Gbps 1:4 LVDS repeater optimized for high-speed signal routing and distribution over lossy FR-4 printed circuit board backplanes and balanced cables.

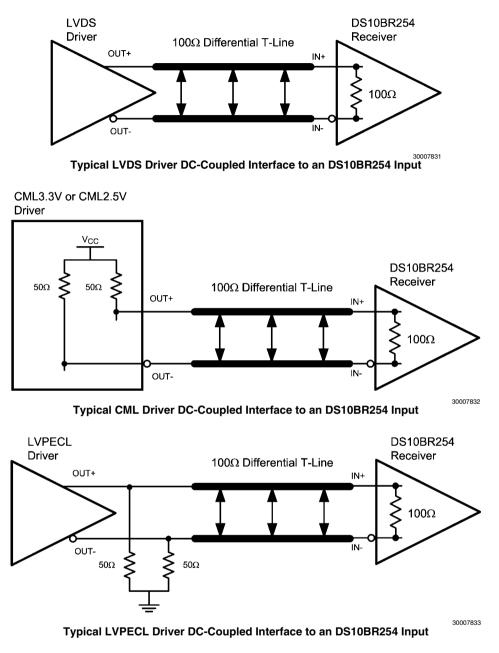
TABLE 1. Input Select Truth Table

CONTROL Pin (SEL_in) State	Input Selected
0	IN1
1	IN2

Input Interfacing

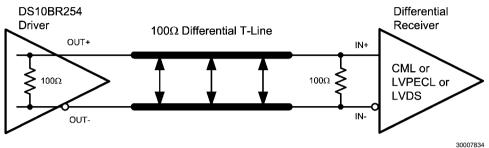
The DS10BR254 accepts differential signals and allows simple AC or DC coupling. With a wide common mode range, the DS10BR254 can be DC-coupled with all common differential

drivers (i.e. LVPECL, LVDS, CML). The following three figures illustrate typical DC-coupled interface to common differential drivers. Note that the DS10BR254 inputs are internally terminated with a 100 Ω resistor.

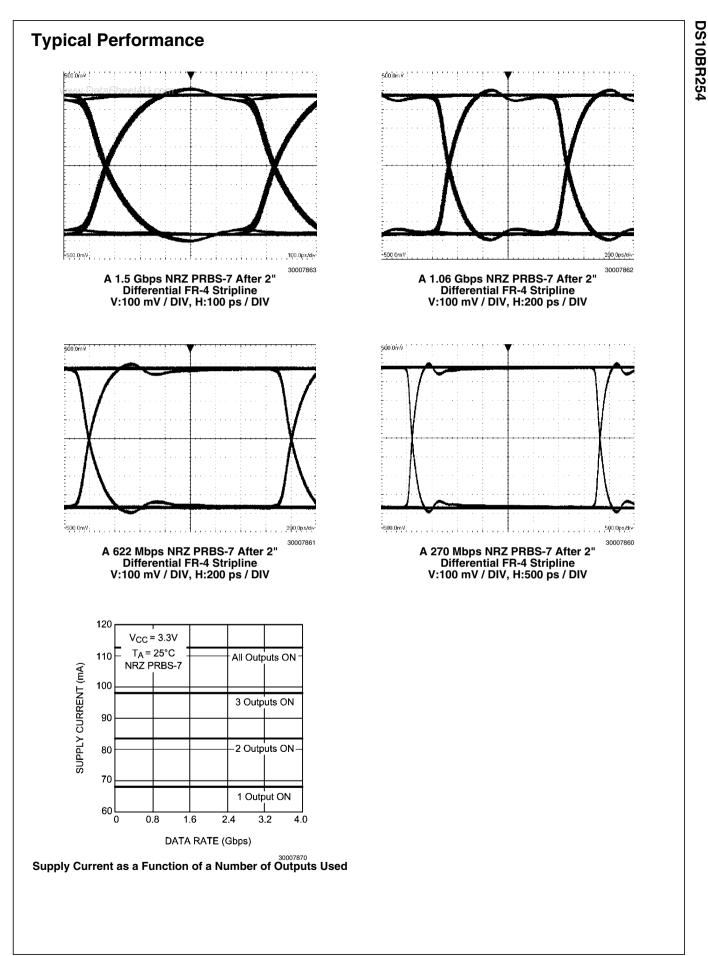


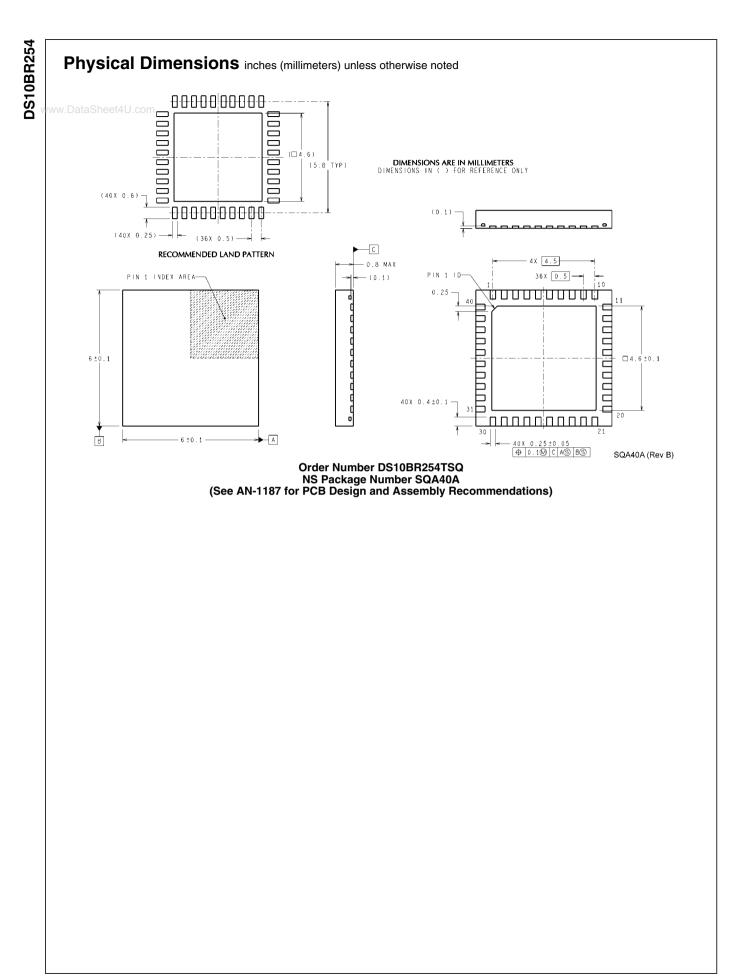
Output Interfacing

The DS10BR254 outputs signals compliant to the LVDS standard. Its outputs can be DC-coupled to most common differwential receivers. The following figure illustrates typical DCcoupled interface to common differential receivers and assumes that the receivers have high impedance inputs. While most differential receivers have a common mode input range that can accomodate LVDS compliant signals, it is recommended to check respective receiver's data sheet prior to implementing the suggested interface implementation.



Typical DS10BR254 Output DC-Coupled Interface to an LVDS, CML or LVPECL Receiver





Notes

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Notes

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LVDS	www.national.com/lvds	Reference Designs	www.national.com/refdesigns		
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